



Applicant(s): Perez, Erasmo; Roman, David T.
Assignee: Amkor Technology, Inc.
Title: Semiconductor Package With Exposed Die Pad And Body-Locking Leadframe
Serial No.: 09/436,158 Filing Date: 11/09/99
Examiner: Unknown Group Art Unit: 2811
Docket No.: M-7744 US

Newport Beach, California
March 7, 2001

COMMISSIONER FOR PATENTS
Washington, D. C. 20231

**INFORMATION DISCLOSURE STATEMENT
UNDER 37 CFR § 1.97(b)**

Dear Sir:

Pursuant to 37 C.F.R. § 1.56, § 1.97 and § 1.98, the documents listed on the accompanying PTO Form-1449 are called to the attention of the Examiner for the above patent application. Copies of these documents are enclosed.

Applicant also directs the Examiner's attention to the following U.S. Patent Applications and the references cited therein:

<u>Serial No.</u>	<u>Status</u>
09 103,760	Issued as U.S. Patent 6,143,981
09 393,016	Pending
09/176,614	Allowed
09 615,107	Pending
09 324,710	Pending

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1. an admission that the documents are necessarily prior art with respect to the instant invention;

2. a representation that a search has been made; or

3. an admission that the information cited herein is, or is considered to be, material to patentability as defined in § 1.56(b).

Applicant believes that no fee is necessary, since the case has not been substantively examined. However, any appropriate fees may be charged to Deposit Account No. 19-2386.

EXPRESS MAIL LABEL NO:

EL661717958US

Respectfully submitted,



Don C. Lawrence
Attorney for Applicant(s)
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